



## Material Content Data Sheet



<b>Sales Product Name</b>		ESD8V0L2B-03L E6327		<b>Issued</b>		4. March 2019		
<b>MA#</b>		MA005097542						
<b>Package</b>		PG-TSLP-3-1		<b>Weight*</b>		0.55 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.16		1648	
	noble metal	gold	7440-57-5	0.004	0.64		6390	
	inorganic material	silicon	7440-21-3	0.043	7.80	8.60	77999	86037
leadframe	non noble metal	nickel	7440-02-0	0.071	12.95	12.95	129514	129514
wire	noble metal	gold	7440-57-5	0.012	2.14	2.14	21409	21409
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.000	0.04		367	
	organic material	carbon black	1333-86-4	0.004	0.74		7350	
	plastics	epoxy resin	-	0.055	9.92		99225	
	inorganic material	silicondioxide	60676-86-0	0.346	62.81	73.51	628058	735000
leadfinish	noble metal	gold	7440-57-5	0.008	1.40	1.40	14020	14020
plating	noble metal	gold	7440-57-5	0.008	1.40	1.40	14020	14020
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com